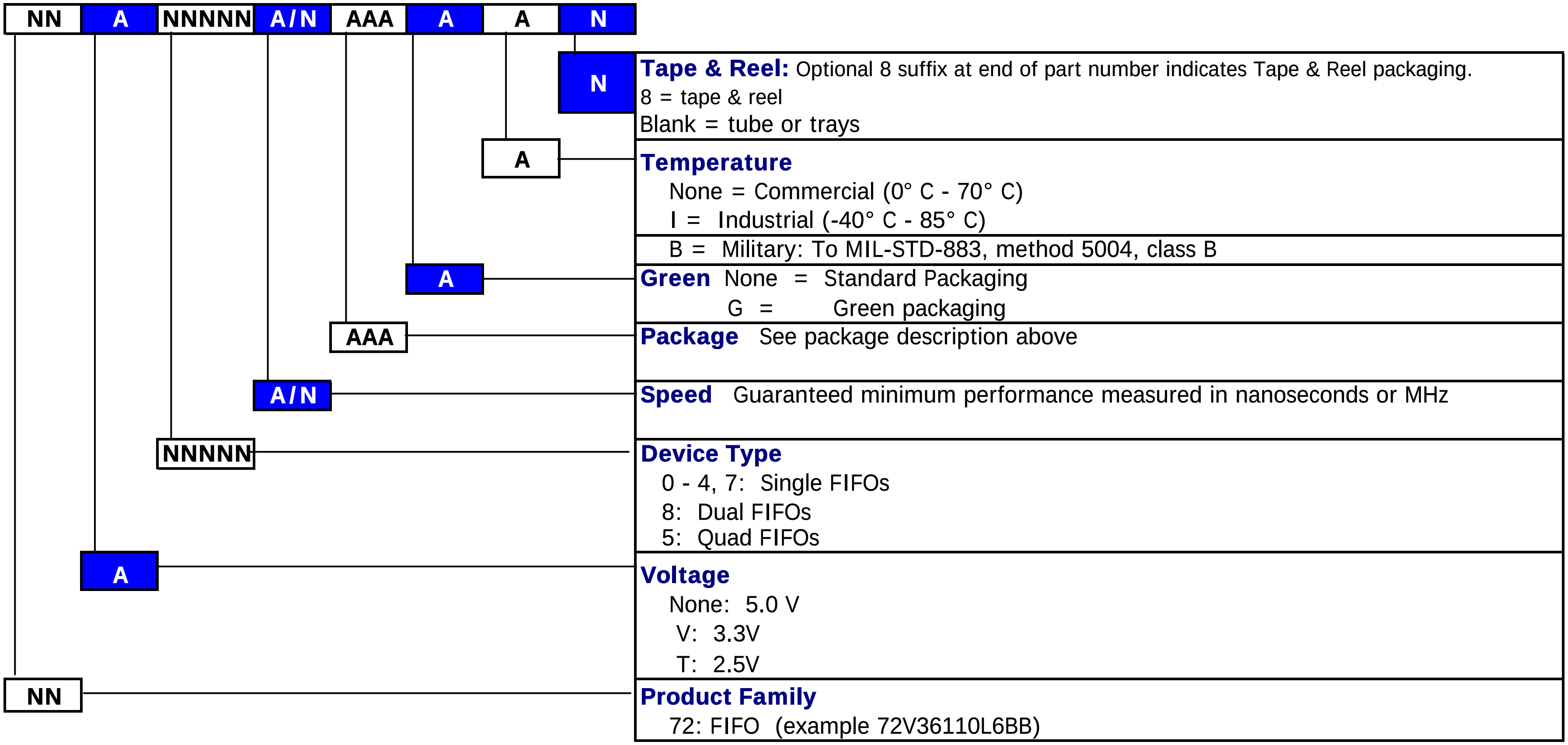
FIFO PRODUCTS
Ordering Information
Package Description Table

IDT ID	Abbr	Description	IDT ID	Abbr	Description
D	CERDIP	Ceramic Dual In-Line Package	TP	PDIP	Plastic Dual In-line Package
TD	CERDIP	Ceramic Dual In-Line Package	J	PLCC	Plastic Leaded Chip Carrier
BC	CABGA	Chip Array Ball Grid Array	PQF	PQFP	Plastic Quad Flat Package
L	LCC	Leadless Chip Carrier (Ceramic) - mil only	SO	SOIC	Small Outline Integrated Circuit (Plastic)
BB	PBGA	Plastic Ball Grid Array	PF	TQFP	PThin Quad Flat Package (Plastic)
BG	PBGA	Plastic Ball Grid Array	TF	TQFP	Thin Quad Flat Package (Plastic)
P	PDIP	Plastic Dual In-line Package	PA	TSSOP	Thin Shrink (Plastic) Small Outline Package

FIFO PRODUCTS
Part Number Description

A = Alpha character N = Numeric character



N — **Tape & Reel:** Optional 8 suffix at end of part number indicates Tape & Reel packaging.
8 = tape & reel
Blank = tube or trays

A — **Temperature**
None = Commercial (0° C - 70° C)
I = Industrial (-40° C - 85° C)
B = Military: To MIL-STD-883, method 5004, class B

A — **Green** None = Standard Packaging
G = Green packaging

AAA — **Package** See package description above

A/N — **Speed** Guaranteed minimum performance measured in nanoseconds or MHz

NNNNN — **Device Type**
0 - 4, 7: Single FIFOs
8: Dual FIFOs
5: Quad FIFOs

A — **Voltage**
None: 5.0 V
V: 3.3V
T: 2.5V

NN — **Product Family**
72: FIFO (example 72V36110L6BB)